

MACHINING APPARATUS AND METHOD OF MANUFACTURING MACHINED
ARTICLE

ABSTRACT OF THE DISCLOSURE

5 The present invention enables a device structure to be simplified and the footprint thereof to be reduced, while at the same time enabling the collection space required to collect objects being machined that have been cut into individual pieces to be reduced, and includes machining tables 2A and 2B that hold a sealed substrate W, a first holding mechanism 3 that holds the sealed substrate W in order for this sealed substrate
10 W to be transported to the machining tables 2A and 2B, a machining mechanism 4 that cuts the sealed substrates W held on the machining tables 2A and 2B into individual pieces, a collection box 5 that, when the sealed substrates W that have been cut into individual pieces by the machining mechanism 4 are dropped into the collection box 5, collects these sealed substrates W, a second holding mechanism 6 that holds products P in
15 order for these products P to be transported from the machining tables 2A and 2B to the collection box 5, a transport moving mechanism 7 that extends in a direction in which the machining tables 2A and 2B and the collection box 5 are aligned, and has a common transfer shaft 71 that is used to move both the first holding mechanism 3 and the second holding mechanism 6, and a machining moving mechanism 8 that moves the machining
20 mechanism 4 within a horizontal plane both in a first direction along the transfer shaft 71 and in a second direction that is orthogonal to the first direction.

Fig. 1